



**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**In re Application of:**

Moden et al.

**Serial No.:** 10/792,222

**Filed:** March 3, 2004

**For: A METHOD FOR FORMING A LOW  
PROFILE MULTI-IC CHIP PACKAGE  
CONNECTOR (as amended)**

**Confirmation No.:** 4777

**Examiner:** M. Trinh

**Group Art Unit:** 3729

**Attorney Docket No.:** 2269-3389.8US  
(97-0638.08/US)

**CERTIFICATE OF MAILING**

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

June 14, 2006  
Date

Signature

Leta M. Howard  
Name (Type/Print)

**AMENDMENT UNDER 37 C.F.R. §1.116**

Mail Stop AF  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

The following amendments and remarks are filed in response to the Examiner's remarks in the Final Office Action mailed April 14, 2006, the three-month shortened statutory period for response to which expires on July 14, 2006. This response is submitted on or before two months from the mailing date of the Final Office Action.

**Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper.

**Remarks/Arguments** begin on page 5 of this paper.